



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

N - CHANNEL ENHANCEMENT MODE POWER MOSFET**TF040N03M****• General Description**

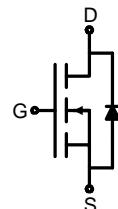
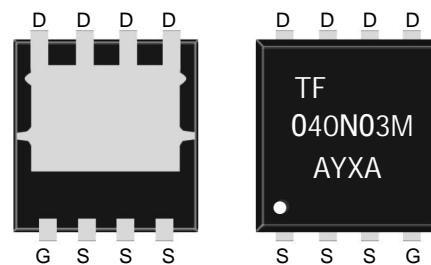
The TF040N03M combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

• Product Summary $V_{DS} = 30V \quad I_D = 60A$ $R_{DS(on)(10V\ typ)} = 4.0m\Omega$ $R_{DS(on)(4.5V\ typ)} = 6.0m\Omega$ **PDFNWB3.3x3.3-8L****• Ordering Information:**

Part NO.	TF040N03M
Marking 1	040N03M
Marking 2	TF:tuofeng; AA:device code; Y:year code; X:Week
MOQ	5000

• Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ T_C = 25^\circ C$	60	A
	$I_D @ T_C = 75^\circ C$	42	A
	$I_D @ T_C = 100^\circ C$	36	A
Pulsed Drain Current ^①	I_{DM}	200	A
Total Power Dissipation	$P_D @ T_C = 25^\circ C$	40	W
Total Power Dissipation	$P_D @ T_A = 25^\circ C$	1.0	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;



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N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TF040N03M

Single Pulse Avalanche Energy	E_{AS}	150	mJ
Avalanche Current	I_{AS} I_{AR}	30	A

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	3.5	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	55	° C/W
Soldering temperature, wave soldering for 8s	T_{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.0	1.7	2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 20A$		4.0	5.0	$m\Omega$
		$V_{GS} = 4.5V, I_D = 20A$		6.0	7.5	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = 25V, I_D = 10A$		18		S
Source-drain voltage	V_{SD}	$I_S = 20A$			1.20	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V$ $f = 1MHz$	-	1615	-	pF
Output capacitance	C_{oss}		-	245	-	
Reverse transfer capacitance	C_{rss}		-	216	-	

•Gate Charge characteristics($T_a = 25^\circ C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Gate Resistance	R_g	$f = 1MHz$		2.1		Ω
Total gate charge	Q_g	$V_{DD} = 15V$	-	42	-	nC
Gate - Source charge	Q_{gs}		-	4.0	-	
Gate - Drain charge	Q_{gd}		-	14	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS} = 10V, V_{DS} = 15V$ $R_G = 3.0\Omega, I = 20A$		7.5		ns
Turn-ON Rise time	t_r			14.5		ns
Turn-Off Delay time	$t_{D(off)}$			35		ns
Turn-Off Fall time	t_f			9.6		ns

Typical Electrical and Thermal Characteristics

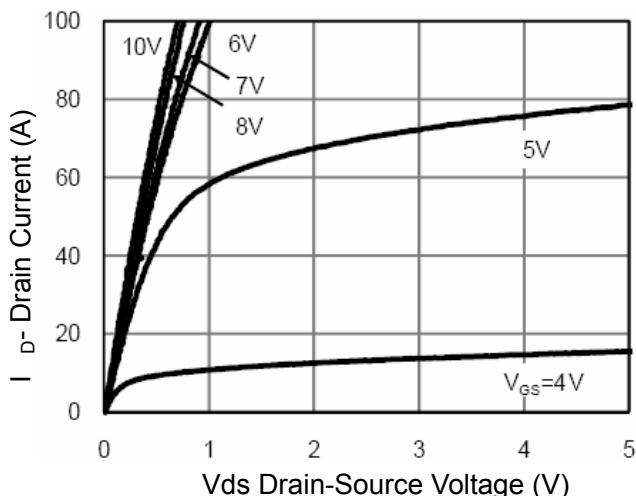


Figure 1 Output Characteristics

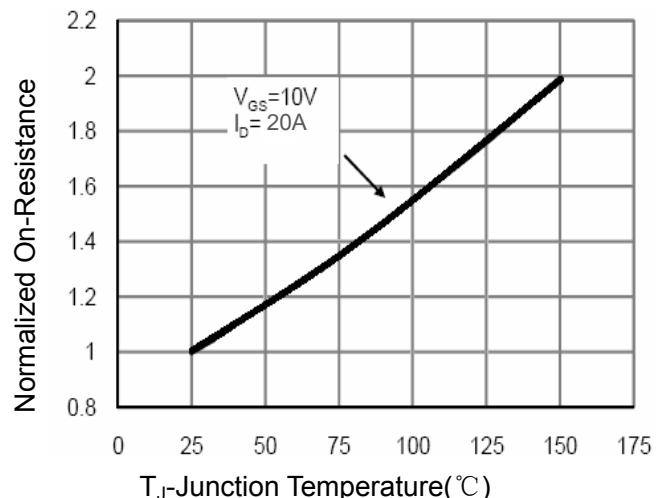


Figure 4 Rdson-JunctionTemperature

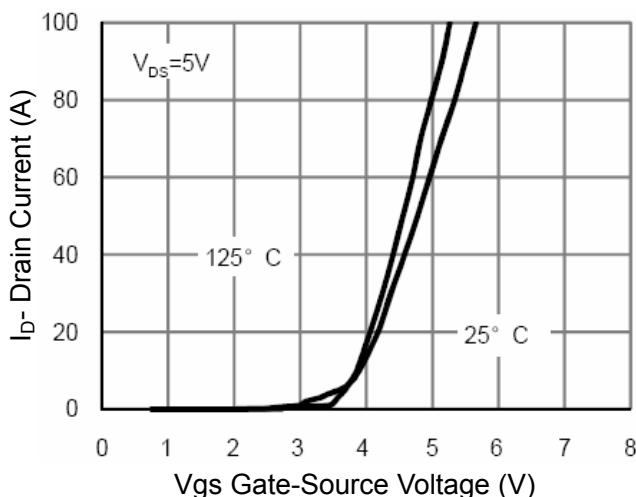


Figure 2 Transfer Characteristics

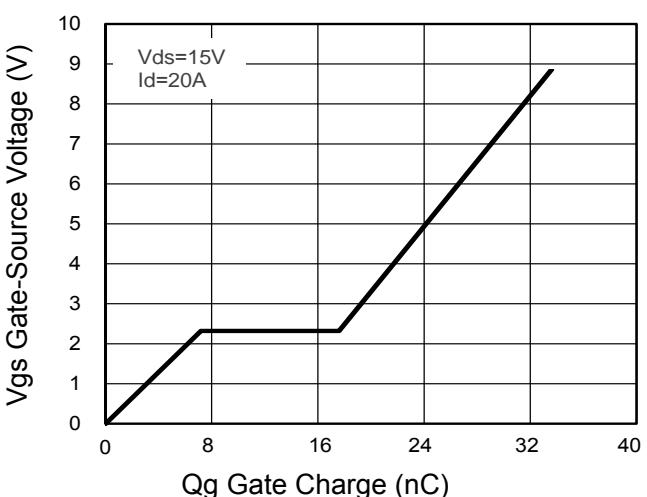


Figure 5 Gate Charge

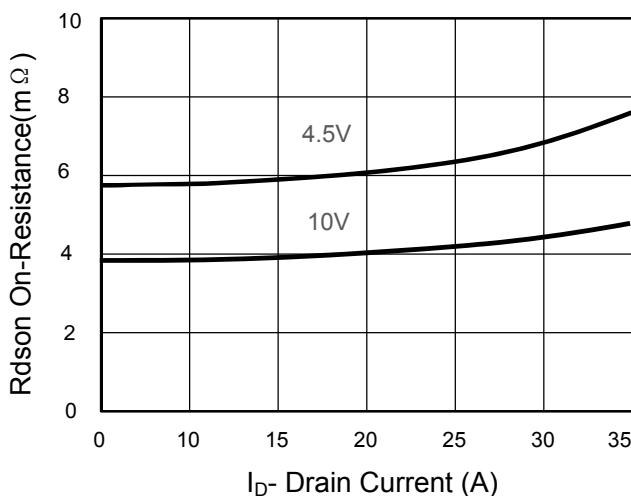


Figure 3 Rdson- Drain Current

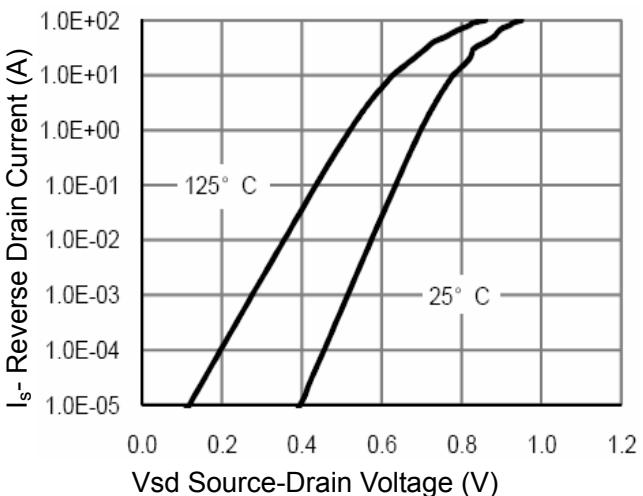


Figure 6 Source- Drain Diode Forward

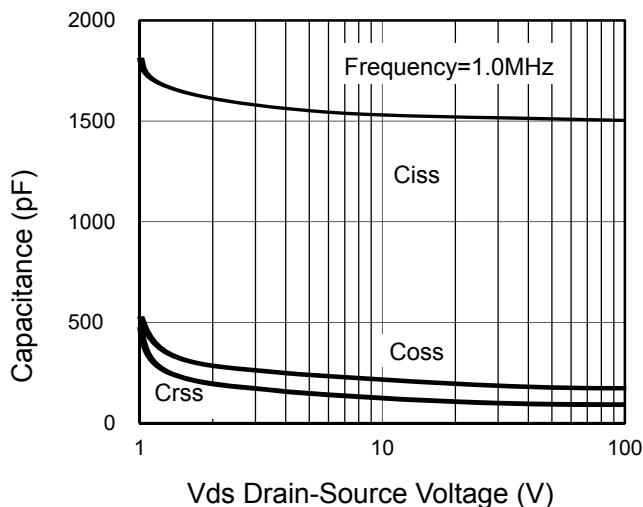


Figure 7 Capacitance vs Vds

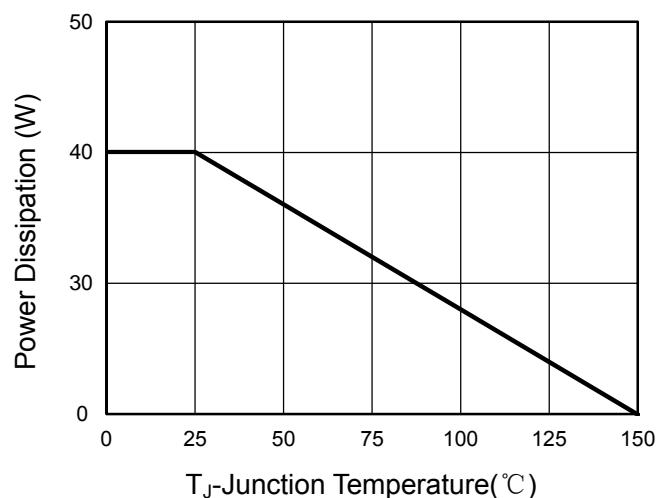


Figure 9 Power De-rating

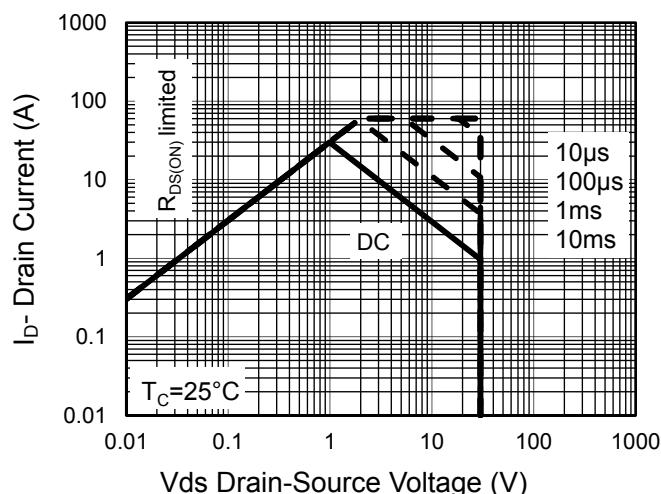


Figure 8 Safe Operation Area

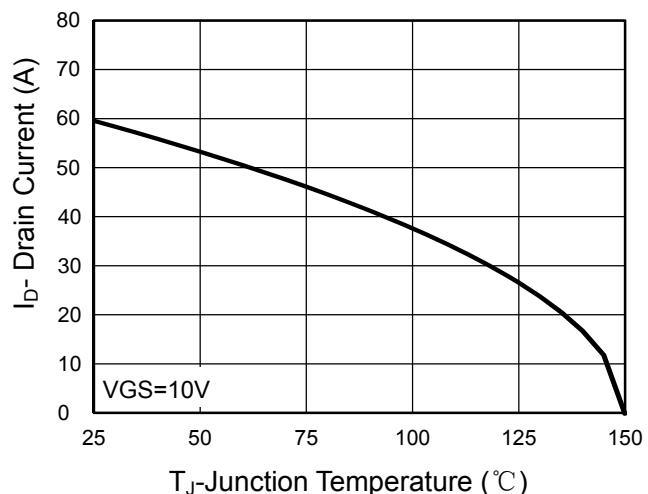


Figure 10 Current De-rating

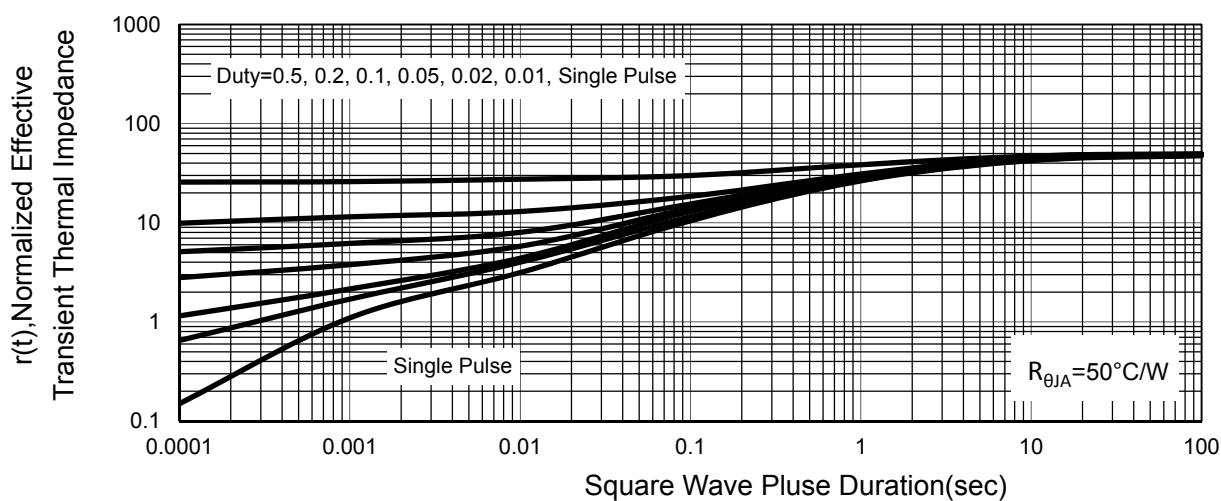


Figure 11 Normalized Maximum Transient Thermal Impedance

Fig.12 Switching Time Measurement

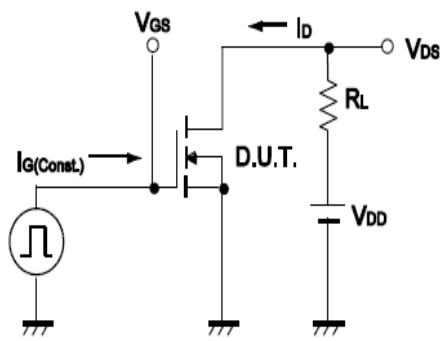
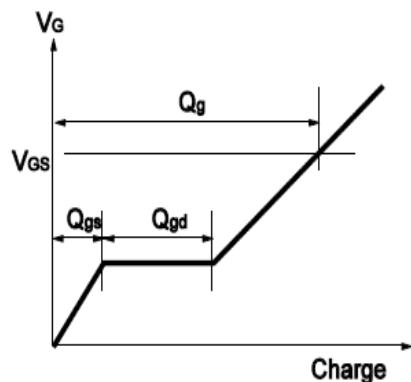


Fig.13 Gate Charge Waveform



Circuit Fig.14 Switching Time

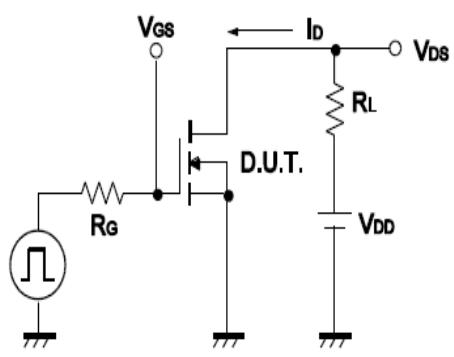
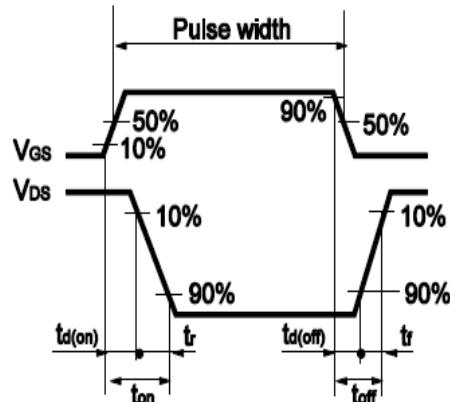


Fig.15 Gate Charge Waveform



Measurement Circuit

Fig.16 Avalanche Measurement Circuit

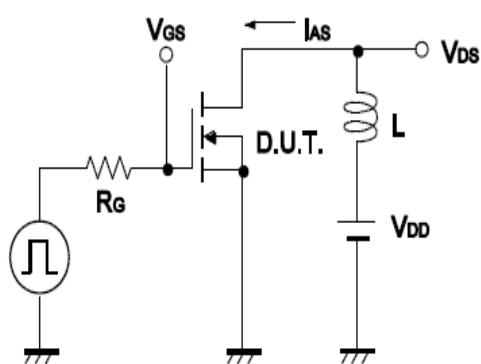
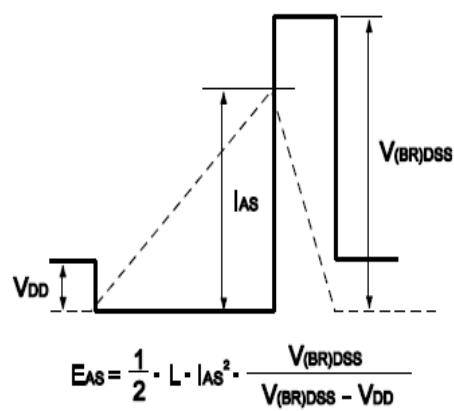
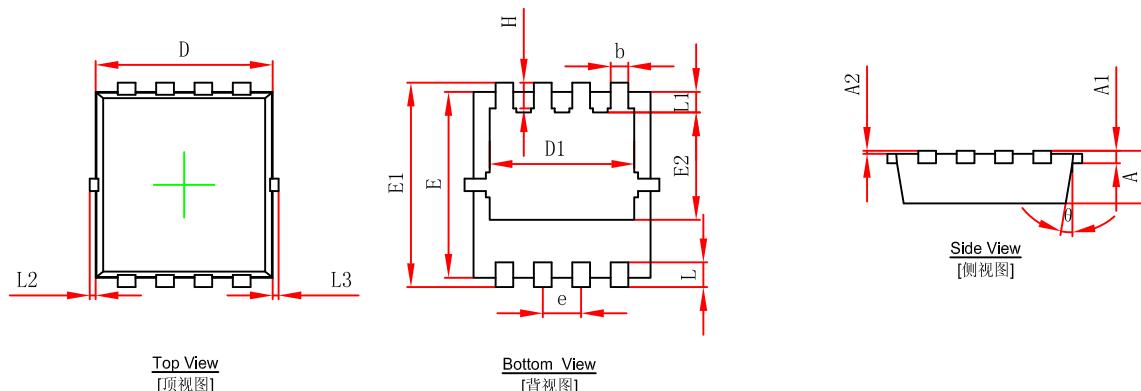


Fig.17 Avalanche Waveform

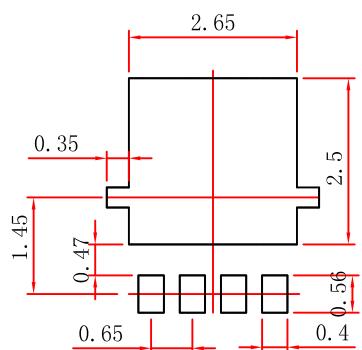


PDFNWB3.3x3.3-8L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°

PDFNWB3.3x3.3-8L Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.